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Please record the attached original	documents or copy thereof			
Name of conveying party(ies)	Name and address of receiving party(ies):			
(1) Shigeyoshi NETSU; and (2) Hisashi MASUMURA	Name: Shin-Etsu Handotai Co., Ltd.			
Additional name(s) of conveying party(ies) attached? ☐ Yes ☑ No	Address: 4-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan			
Nature of conveyance:	Additional name(s) & address(es) attached?			
	☐ Yes			
Execution Date: (1) & (2) April 4, 2002				
4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: April 4, 2002 A. Patent Application No.(s) To be assigned. B. Patent No.(s)				
Additional numbers attached? ☐ Yes ☑ No				
5. Name and address of party to whom correspondence concerning document should be mailed:	Total number of applications and patents involved: <u>One</u>			
Name: Rader, Fishman & Grauer, PLLC	7. Total fee (37 CFR 3.41) \$ 40.00			
Street Address: 1233 20th Street, N.W., Suite 501	☐ Charged to Deposit Account No. 18-0013			
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Docket No.	

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

[Insert Shin-Etsu Handotai Co., Ltd.

of 4-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

WAFER MANUFACTURING METHOD, POLISHING APPARATUS,

AND WAFER

Name(s) Address(es)]

Title of

Invention

[*If the assignment

is being filed after the

filing of the application, this section must be completed]

[Signature(s)]

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

*filed on October 22, 2001, Serial No. PCI/JP01/09240

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, division, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

Shigerish Netsu Apr. 4, 2002 Shigeyoshi NETSU (TYPE NAME) (DATE) Hisashi MASUMURA Apr. 4, 2002 masumur (TYPE NAME) (SIGNATURE) (DATE) (SIGNATURE) (TYPE NAME) (DATE) (TYPE NAME) (SIGNATURE) (DATE) (TYPE NAME) (SIGNATURE) (DATE) (TYPE NAME) (SIGNATURE) (DATE)

NO LEGALIZATION REQUIRED

RECORDED: 07/23/2002

PATENT REEL: 013284 FRAME: 0417